REACTIVE EVAPORATION OF TiO2 AND SiO2 FILMS FOR MULTILAYER COATINGS

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ABSTRACT

The optimum deposition parameters for TiO_2 and SiO_2 films for the multi-layer coatings are reported. The influence of residual pressure of oxygen in the range of 10^{-4} – 10^{-5} torr, rate of evaporation between 1 and 22 Å sec⁻¹ and different oxides of titanium on the refractive index and transmittance of quarter wave films are studied. The characteristic absorption peaks are at $7.0\,\mu$ for TiO_2 and $9.5\,\mu$ for SiO_2 . 11 to 21 layers of quarter wave multilayer stacks were tested for their durability and stability and found to be good.

Keywords. TiO₂ and SiO₂ films; Optical properties; Reactive evaporation; Multilayer films of TiO₂ and SiO₂; and Laser Mirrors.

1. Introduction

Multilayer dielectric films find a wide application in several optical devices and instruments. The multilayer stack consists of alternate layers of high and low refractive index materials such as, ZnS $(2\cdot3)$, ZnSe $(2\cdot5)$, TiO₂ $(2\cdot3)$, MgF₂ $(1\cdot38)$, Cryolite $(1\cdot33)$ and SiO₂ $(1\cdot50)$. Most of the films except those of the oxides are soft in nature and sensitive to different environmental conditions. Multilayer stacks produced with the TiO₂ and SiO₂ combination are mechanically, chemically and thermally stable and are known as "hard coatings".

Films of these oxides can be prepared either by reactive evaporation of lower oxides such as TiO, SiO in the presence of oxygen or by electron beam evaporation of TiO₂ and SiO₂. In the process of reactive evaporation, the sub-oxide vapours and the oxygen molecules will arrive onto the substrate simultaneously and react with each other forming a strongly oxidised film, when the mean free path of the oxygen molecules is greater than the source to substrate distance.

According to Auwarter [1] non-absorbing and durable TiO2 and SiO2 films can be obtained if the partial pressure of oxygen in the chamber is in the range of 7×10^{-5} to 9×10^{-5} torr and also the direction of flow of the oxygen molecules and the vapours must be the same. Ritter [2] observed Oxygen more since the film produced by evaporation of SiO in the Si₂O₃ as a main phase in the film produced by evaporation of SiO in the presence of oxygen at 1×10^{-4} torr. SiO₂ films produced by electron beam evaporation of quartz are free from absorption down to 0.2μ whereas Si_2O_3 films absorb below 0.3μ . The reported values of refractive indices for silicon oxide films, vary from 2.0 to 1.46 as the phase of the film changes from SiO to SiO₂. Anastasio [3] and Howson et al. [4] found that there is an unique relationship between the properties of Silicon oxide film and the parameter p/r which is defined as the ratio of oxygen molecules to the vapour molecules, where $p/r = 1.06 \times 10^6 \times P/R$ where P is the partial pressure of oxygen in torr and R is the deposition rate in A sec⁻¹. Further, they observed that the three phases SiO, SiO₂, Si₂O₃ could be obtained by varying the values of p/r, with the values larger than 10 favouring the formation of SiO₂ phase.

Investigations of Ritter [5] on TiO2 films showed that the refractive index and the hardness of the films decreased with an increase of oxygen pressure. Dundenhausen et al. [6] studied the effect of substrate temperature on refractive index of reactively evaporated films of TiO2 and reported that the refractive index of TiO2 films was 1.9 when the substrate was at room temperature and 2.8 at 400° C. Heitman [7, 8] introduced ionized oxygen instead of neutral oxygen to improve the oxidation during the deposition of TiO2 and SiO2 films and produced non-abosrobing, durable films with the evaporation rate of 3 Å sec-1 for TiO and 5 Å sec-1 for SiO. The corresponding refractive indices were reported as 2.3 and 1.42 at 5500 Å. Also, he observed that TiO₂ and SiO₂ films exhibit opposite stresses and therefore it could be possible to produce multilayers with low residual stresses using the above combination.

In view of the profound influence of evaporation parameters such as oxygen pressure, evaporation rate and substrate temperature on the properties of the films in the reactive evaporation technique, electron beam evaporation technique has been preferred for the production of multilayer films with TiO₂ and SiO₂. Inspite of the advantage in producing stable and pure films of oxides, the electron beam technique leads to undesirable scatter centres and damage sites in the films. However the potentialities of the reactive evaporation technique need not be ruled out in view of the simplicity both in technique and evaporation. It could also be observed

that the limited or no information exists in the published literature on the fabrication of multilayer stacks with the oxides of titanium and silicon by either of the techniques. Hence it is proposed to adopt the reactive evaporation technique to study the optimum deposition parameters to produce reliable multilayer films of TiO2 and SiO2 with desired properties. The optical properties of individual films of TiO2 and SiO2 have been studied by varying the deposition parameters to find the suitable conditions for matching these films for the production of the multilayer films [9, 10]. Durable single layer films were deposited with the evaporation rate of 2.5 Å sec-1 and 5 Å sec.-1 of TiO and SiO respectively at the oxygen pressure of 1×10^{-4} torr and the substrate being at room temperature. The corresponding refractive indices were measured and found to be 2.30 and 1.50 at 6328 Å.

These optimized parameters have been used in the fabrication of dielectric mirrors consisting of 21 alternate layers of TiO2 and SiO2 and with the transmission 0.05%.

2. EXPERIMENTAL TECHNIQUES

Titanium dioxide and silicon dioxide films were produced in conventional 19" vacuum coating plant. The films were deposited on well polished B.S.C. glass and on fused quartz substrates for the optical measurements in both visible and ultra violet regions respectively. The substrates are first cleaned with liquid detergent using soft linen cloth and then rinsed in tap water followed by distilled water and deionised water. Then the substrates are vapour degreased in trichloroethylene bath, after which they were immediately transferred to the deposition plant. The materials TiO and SiO used for the evaporation are supplied by Balzers. Tantalum boat with a perforated cover, was used for the evaporation of SiO and a tungsten boat for evaporating Ti, TiO, Ti₂O₃ and TiO₂. In all these experiments the bell jar was evacuated to a pressure less than 1×10^{-6} torr. Then the oxygen was admitted into the bell jar and maintained at the desired pressure by means of a needle valve. The films of quarter wave thicknesses were monitored using a modulated beam photometer.

The refractive index of the titanium dioxide films were calculated from the transmission measurements of the coated substrates [11]. The transmittance T of an uncoated substrate [12] is given by:

$$T = \frac{1 - R}{1 + R} \tag{1}$$

where R is the reflectance for normal incidence of substrate single surface. where R is the located with a non-absorbing film of reflectance, R_f , the transmittance T_f of the film is given by

$$T_f = \frac{(1-R)(1-R_f)}{(1-RR_f)}$$
 (2)

combining the equations (1) and (2) R_f is given by

$$R_f = \frac{2(T/T_f) - 1 - T}{2(T/T_f) - 1 + T}$$
(3)

Also the transmittance T_f of the coated substrates will be a minimum when $n_f > n_s$ and the optical thickness of a film is $m(\lambda/4)$, $m = 1, 3, 5 \cdots$ where λ is the desired wavelength, n_f , n_s are the restractive indices of the film and the substrate respectively. Titanium dioxide films were deposited to a quarter wave thicknesses at 6328 Å and the ratio T/T_f was measured using a Unicam SP 700 double beam UV and visible spectrophotometer. transmittance of the substrate was calculated from the Fresnel's equation for normal incidence. The values thus obtained for T and T/T_f are substituted in equation (3) to determine R_f . The refractive index n_f [11] of the filmis now calculated using the equation,

$$n_f^2 = n_s \left[\frac{1 + \sqrt{R_f}}{1 - \sqrt{R_f}} \right] \tag{4}$$

The above measurements of n_f is accurate to ± 0.005 . The refractive index of silicon oxide films was determined by Abeles [11] method. method rests on the fact that in the absence of significant optical absorption, the reflectance of p-polarized light from the film is the same as that of the bare substrate for a particular angle of incidence. The refractive index of the film n_f is given by

$$n_f = n_0 \tan \phi_0 \tag{5}$$

where n_0 is the refractive index of the medium of incidence and ϕ_0 is the angle of incidence. The angle ϕ_0 was measured by photo-electric Ellipsometer. The measurements are accurate to ± 0.002 . This method applies accurate rately to the film where the difference of n_f is not greater than 0.3 of that of the substrate.

The I.R. transmission characteristics of the films between 2μ and Corl14 \mu were studied by depositing films on NaCl substrates and using Carl Zeiss I.R. 10 infrared spectrophotometer. In the above experiments film thicknesses were measured using multiple beam interferometer built in the laboratory.

3. RESULTS AND DISCUSSION

Titanium Dioxide Films (i)

Figure 1 represents the variation of transmittance of titanium dioxide and silicon dioxide single layer films of quarter wave thickness at 6328 Å at different wavelengths. U.V. absorption edge was observed at 0.38μ and the refractive index of the film was calculated from the transmission curve was 2.30 at 6328 Å. Due to heat treatment the transmission of the TiO2 film has not changed singificantly in the visible region but has increased slightly at the U.V. edge without any shift in the absorption peak. U.V. absorption edge was observed at 0.32μ for SiO₂ film.

Figure 2 shows the dependence of refractive index of TiO₂ films produced by evaporating Ti, TiO, Ti₂O₃ and TiO₂ in oxygen atmosphere at different pressures between 1.0×10^{-5} torr to 5×10^{-4} torr. When titanium monoxide was evaporated at O_2 pressures lower than 7.5×10^{-5} torr the film became absorbing. Similarly for Ti and Ti₂O₃ the pressure region is indicated as dotted line in Fig. 2 where the absorbing films are obtained. This phenomena might be due to the presence of metallic titanium obtained by the partial dissociation of evaporant or insufficient oxygen for recombination. When these absorbing films were heated to 400° C for 4 hours in air, they were found to be non-absorbing. The values of the refractive index of the above heat treated films are also shown as the dotted curve. The optimum pressures required for Ti, Ti₂O₃ are 2 × 10⁻⁴ and 5×10^{-5} torr respectively for obtaining non absorbing films. However, a high temperature is required for evaporating TiO₂ which results in thermal dissociation of TiO₂. These films are porous and having low refractive index. Figure 3 shows the relation between the refractive index and the wavelength of TiO₂ films at two evaporation rates. The refractive index decreases with increasing wavelengths.

(ii) Silicon Oxide Films

Figure 5 shows the evaporation rate versus the refractive index of the silicon oxide films. During the evaporation of the films, the pressure of oxygen was maintained at 1×10^{-4} torr. Due to heat treatment the values of the refractive index of the films have decreased for the deposition rates above 5 Å sec-1 whereas the values increased for the films deposited at

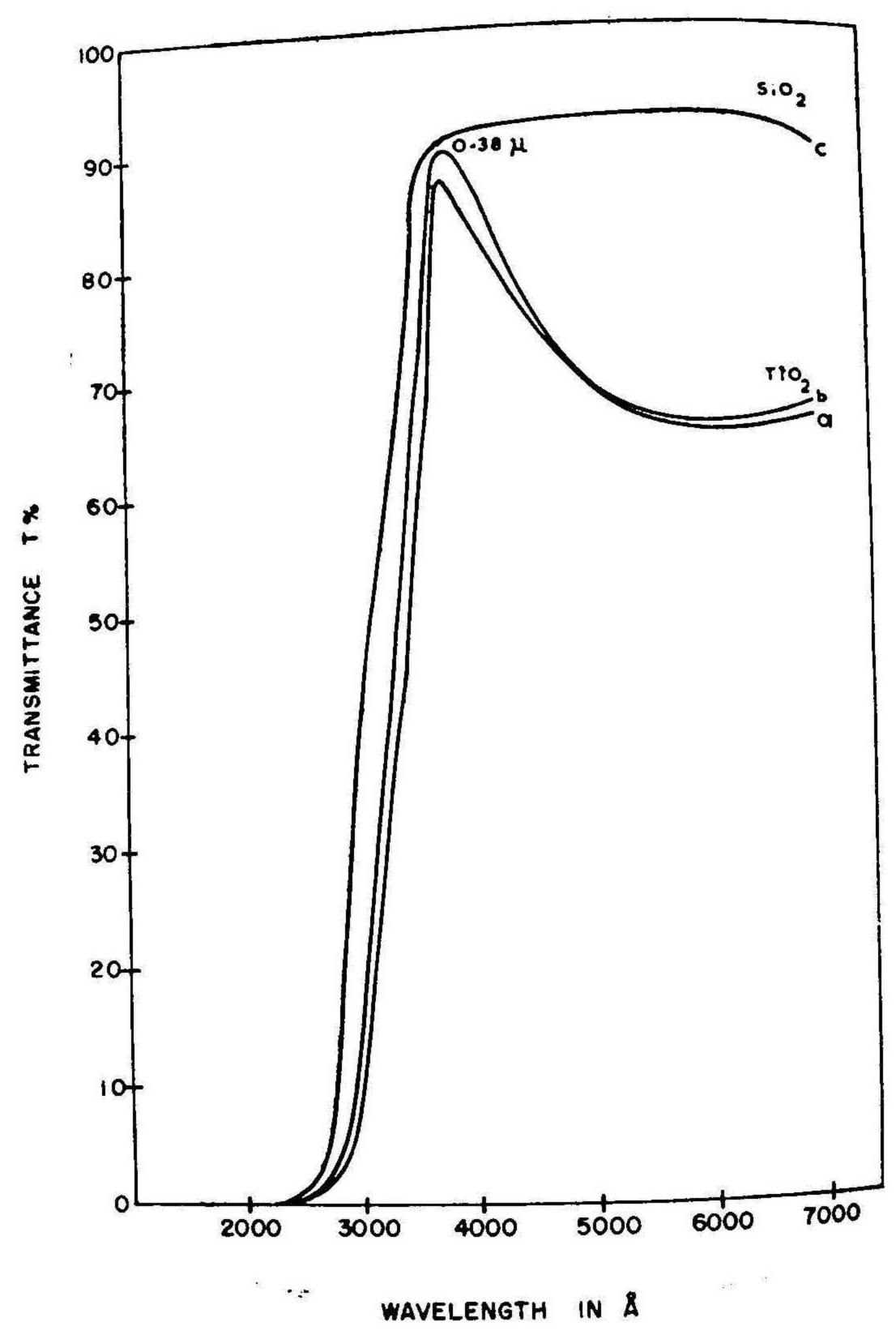
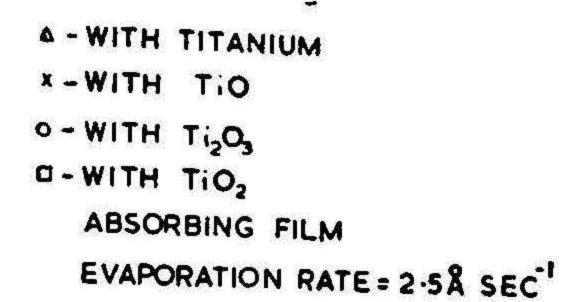


Fig. 1. Transmittance of TiO₂ and SiO₂ films of quarter wave thickness at 6328 Å. (a) TiO₃ film condensed on substrate at room temperature, (b) Effect of heat treatment on the same TiO₃ film at 400° C for 4 hours in air.



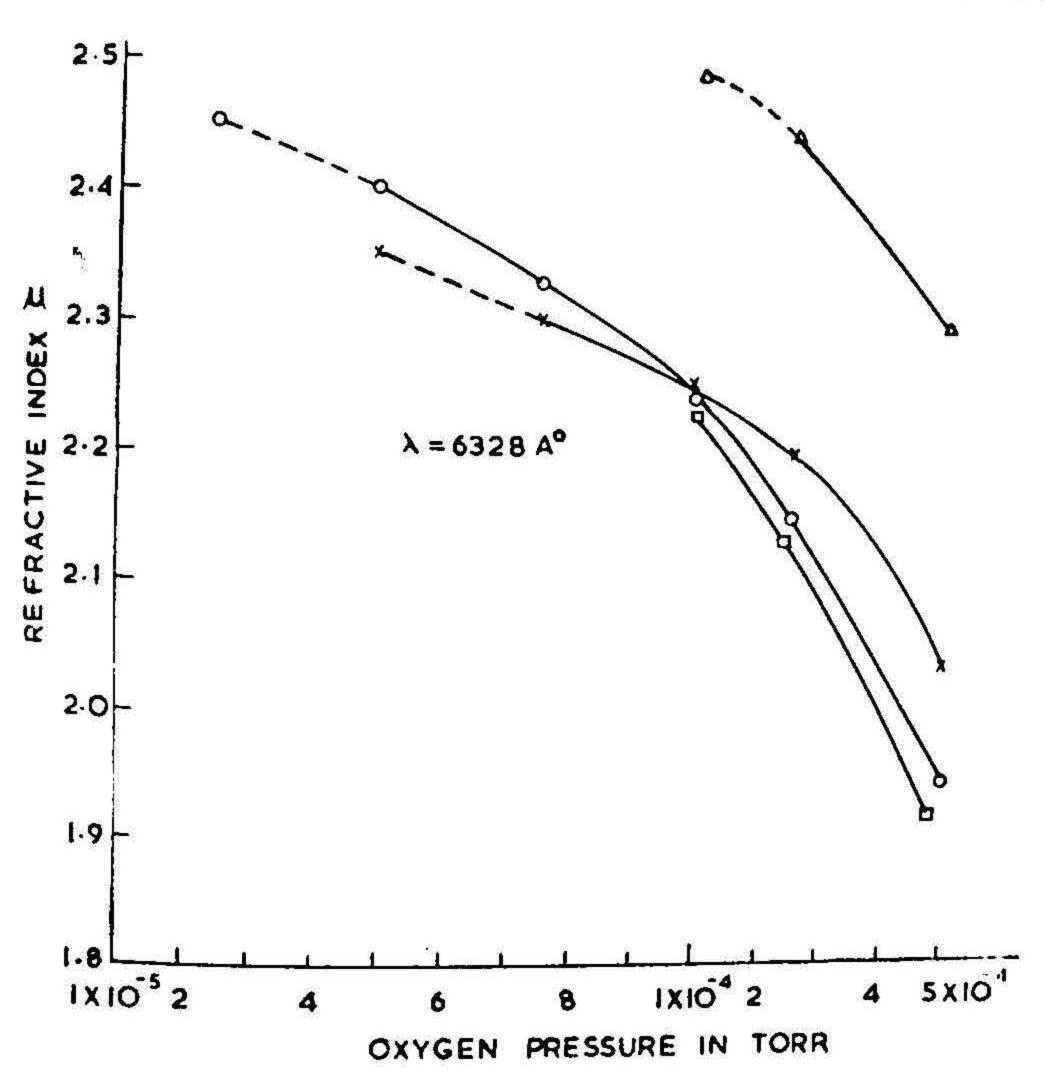


Fig. 2. Refractive index of titanium dioxide films with pressure.

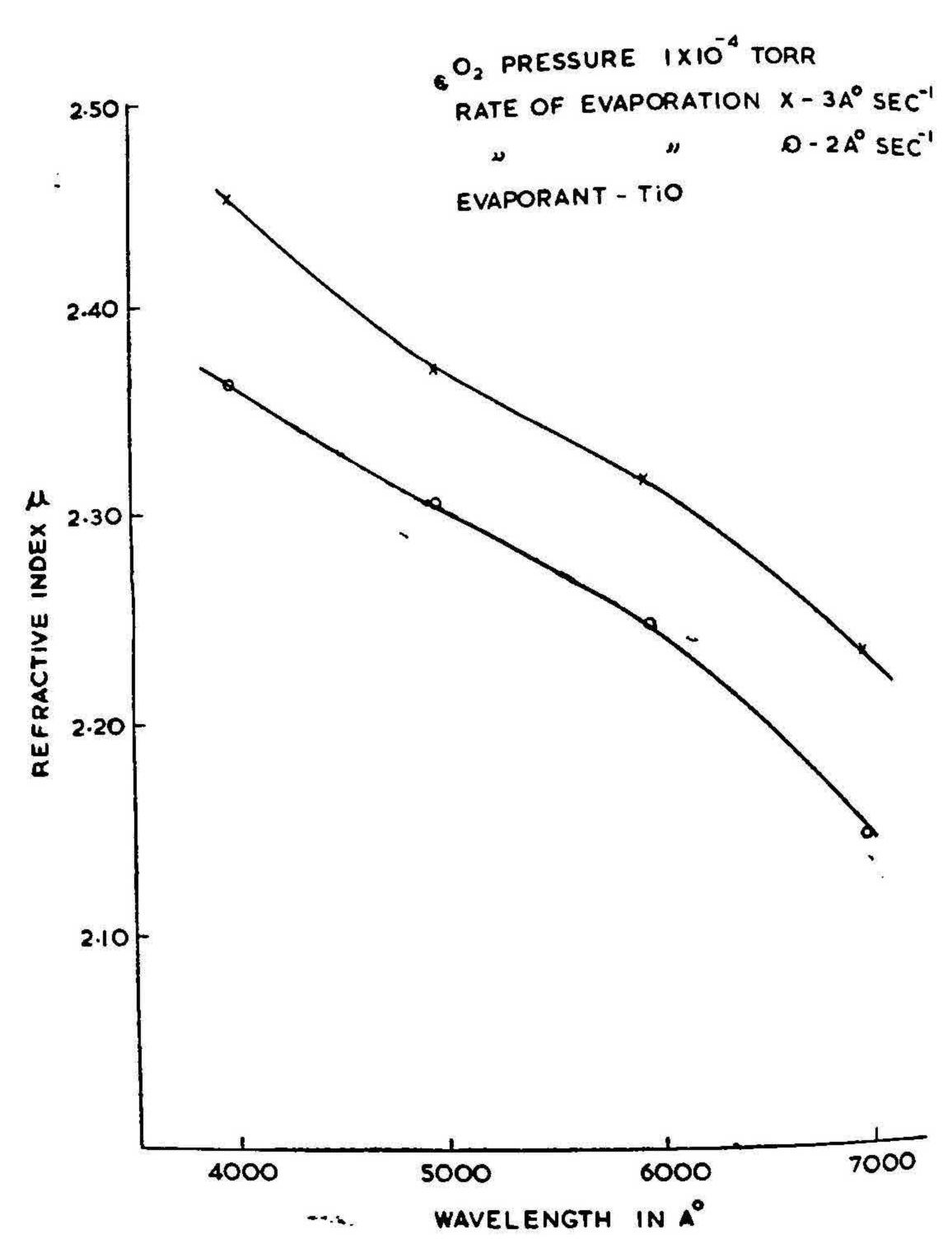


Fig. 3. Refractive index of TiO₂ films deposited at 1 × 10⁻⁴ torr with wavelength.

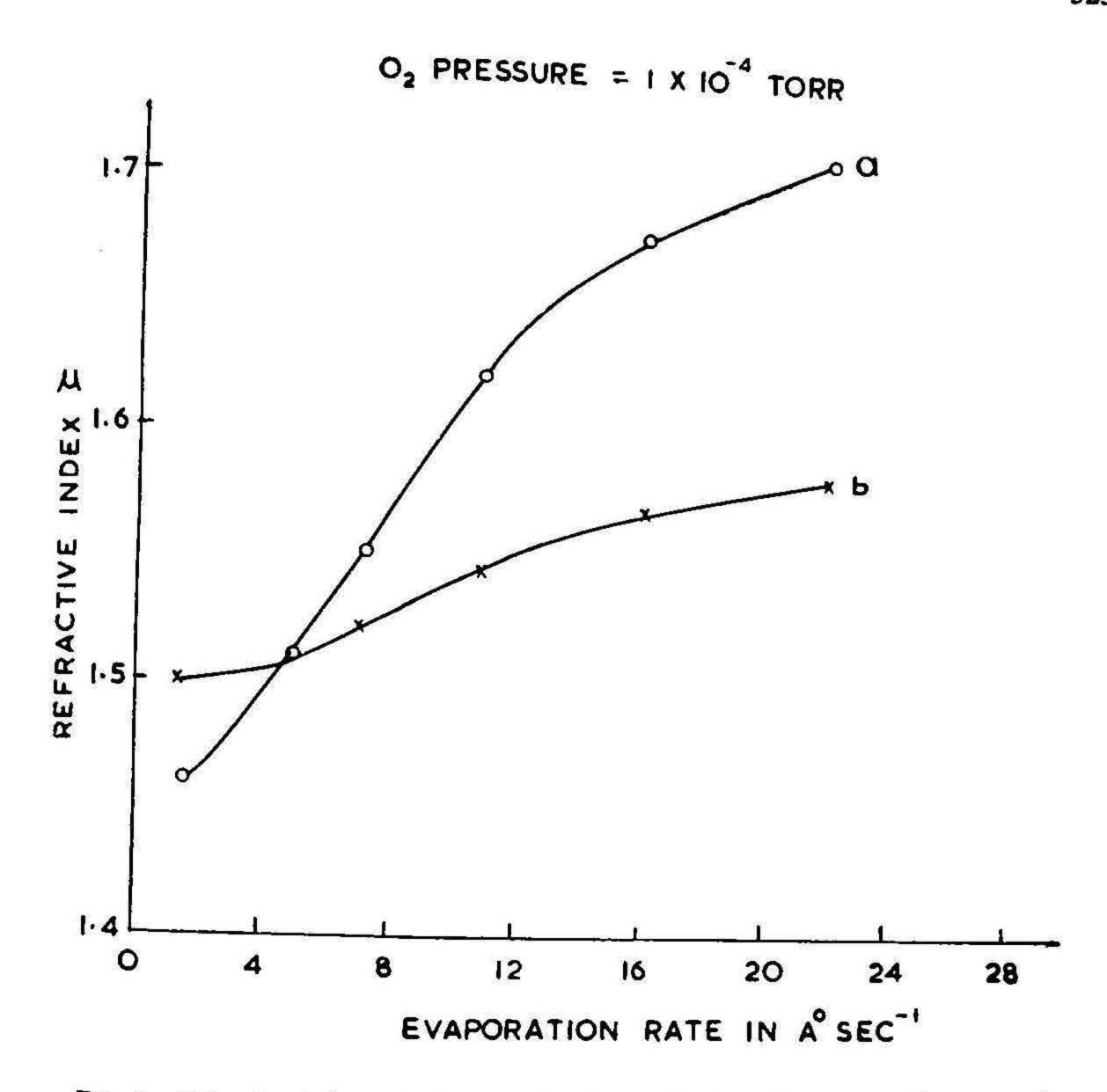


Fig. 4. Refractive index of silicon oxide films with deposition rate. (a) condensed on the substrate at room temperature; (b) Effect of heat treating the film at 250° C for 10 hours.

lower rates. The above phenomenon may be explained on the basis of the conversion of lower oxides to higher oxides in the case of low refractive index films and the transformation of the loosely bound structure to the closed packed one for higher refractive index films. Some of the related optical properties of silicon oxide films are summarised in Table I with the varied deposition parameters. Keeping the pressure at 1×10^{-4} torr the refractive index has increased with the increase of rate of deposition.

Figure 5 represents the infrared transmittance of TiO_2 film and silicon oxide films for three samples deposited under different conditions, between 2μ and 14μ . Curve (A) represents the SiO phase deposited at the oxygen

TABLE I Optical properties of silicon oxide films by evaporating SiO

	pircus post	rties of strice	H-22	Strong absorption edges		
Sample No.	Pressure in torr	Deposition rate in Å sec ⁻¹	I I ICKILOSS	Refractive index at 6328 Å	UV regioι in μ	I.R. region in μ
	22	2700	1 · 71	0.40	9.68	
1	1 × 10 ⁻⁴	7	3000	1.55	0.33	9.56
2	1×10^{-4}		3150	1 · 50	0.32	9.50
3	1×10^{-4}	5	NAME OF THE PARTY	1 · 46	0.30	9.37
4	1×10^{-4}	1.5	3300			
5	1×10^{-5}	17	2525	1.90	0.51	10.0

pressure of 1×10^{-5} torr and at the rate of $17 \,\text{Å/sec}^{-1}$. It has a characteristic absorption peak at $10\,\mu$ and the U.V. absorption edge at $0.51\,\mu$. The refractive index of the film was measured and found to be 1.9. Curve (B) represents the Si₂O₃ phase obtained when the deposition rate is 7 Å sec-1 and oxygen pressure at 1×10^{-4} torr. The strong absorption band at $9.56 \,\mu$, the weak band at $11.5\,\mu$ and UV edge at $0.33\,\mu$ are observed. These results confirm the validity of the earlier results except a slight shift of UV edge to $0.33 \,\mu$ instead of $0.3 \,\mu$. Curve (C) represents silicon oxide film of refractive index 1.46 with a weaker absorption band at 11.8μ . Even though this refractive index value corresponds to bulk SiO2, the IR absorption band $(11.8\,\mu)$ deviates from the reported value of $12.5\,\mu$ for SiO₂ film obtained by electron beam evaporation of quartz. This discrepancy may be explained on the basis of the presence of a small amount of Si₂O₃ in SiO₂ films. The above film corresponding to curve (C) was deposited with the rate of 1.5 Å sec-1 and the oxygen pressure of 1 × 10-4 torr. Curve D is the I.R. transmission of TiO₂ film. Absorption bands were observed at $3.2\,\mu$ and $7.0\,\mu$ when the rate of evaporation is $2.5\,\text{Å}$ sec⁻¹ and the oxygen pressure is 1×10^{-4} torr.

(iii) Multilayer Films

Figure 6 shows a comparison of the experimental curves of transmittance with wavelength for multilayer high reflecting mirrors with 11 to 21 alternate layers of TiO₂ and SiO₂. Quartz substrates were held at

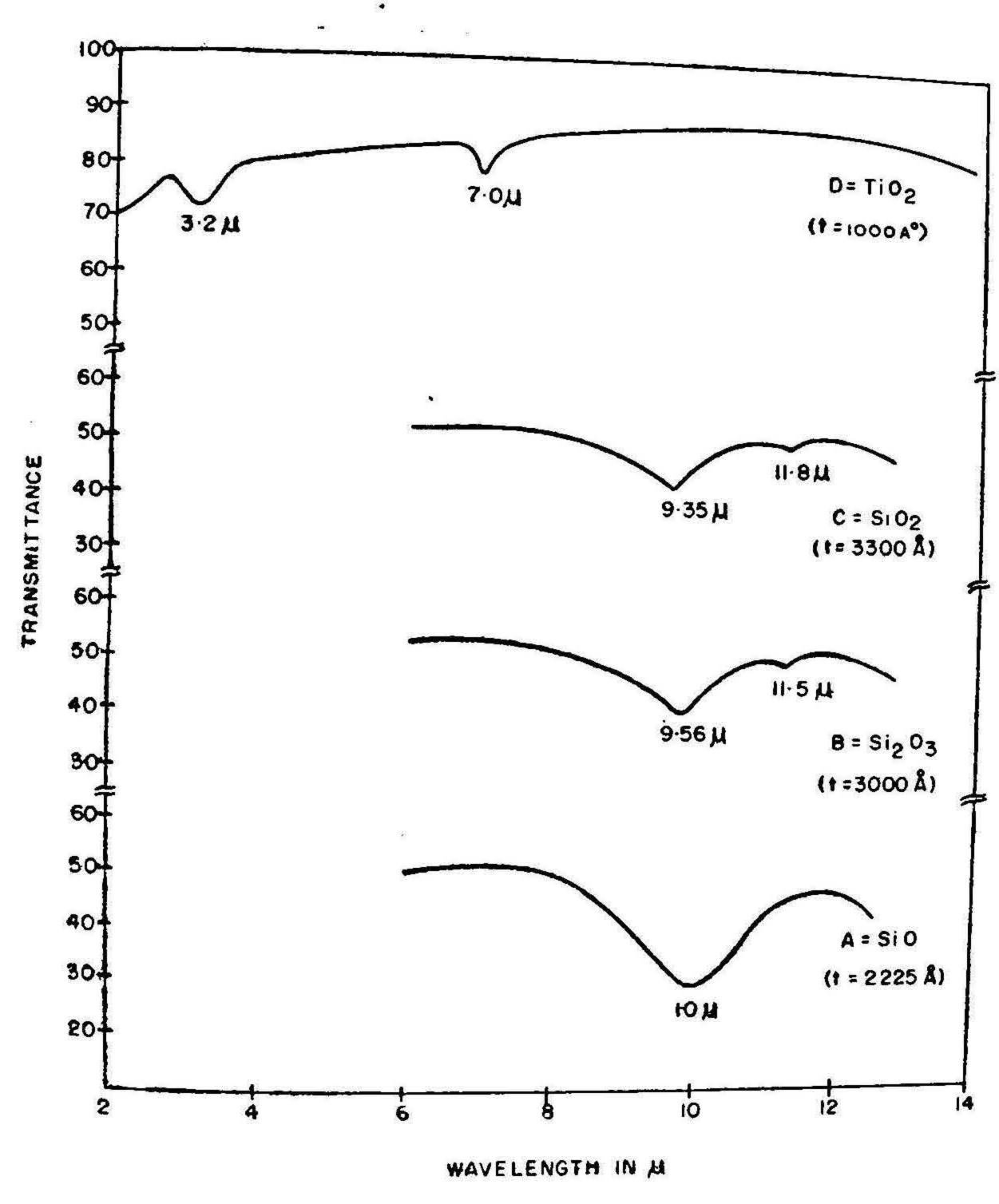


Fig. 5. Infrared transmittance of silicon oxide and TiO₂ films.

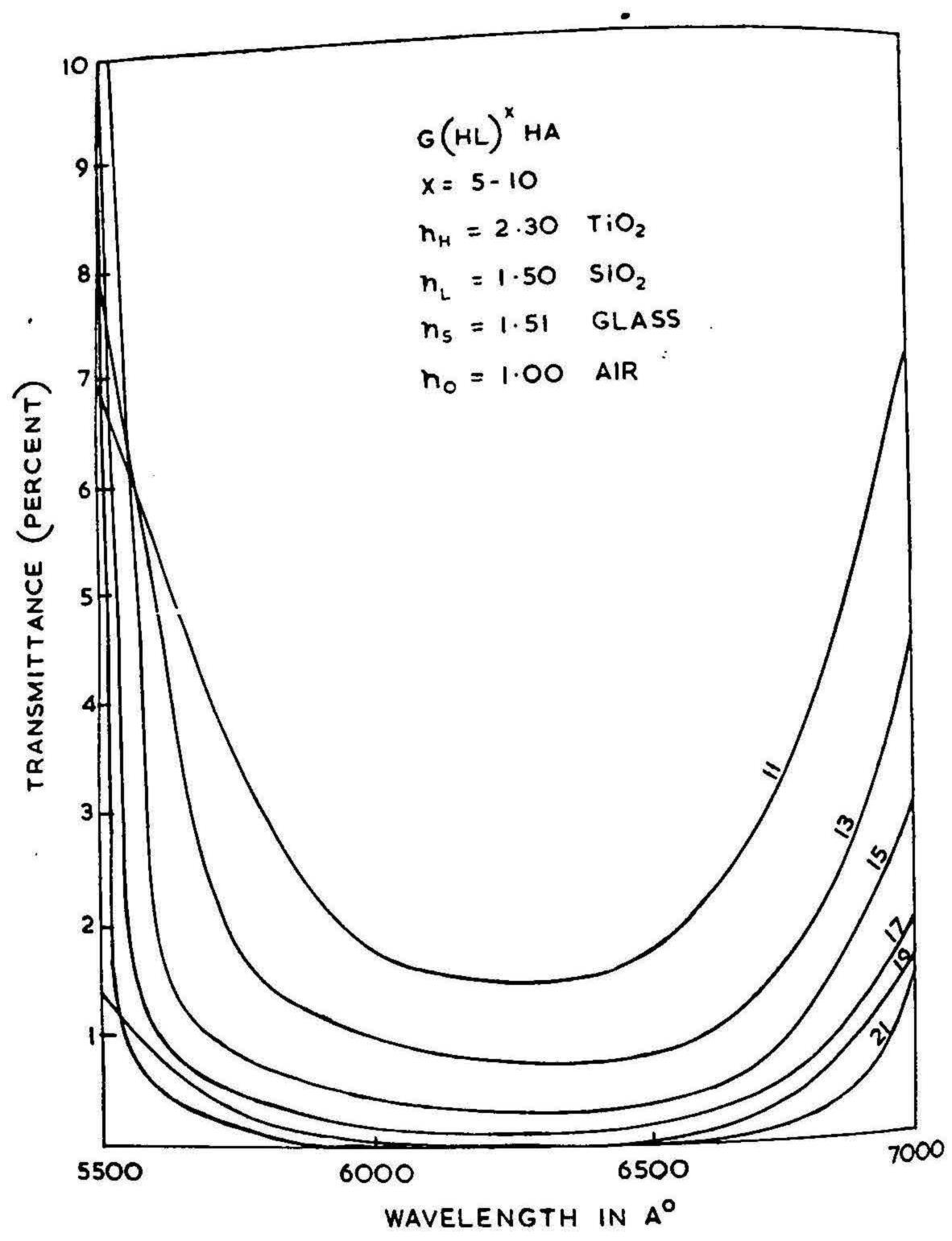


Fig. 6. Experimental curves of transmittance verses wavelength with TiO₂ and SiO₂.

No. of layers	Transm	ission		
	Experimental	Theoretical	Evaporation conditions	
3	38.80	38 · 60	Rate of evaporation:	
5	18.80	18.67	$TiO_2 = 2.5 \text{ Å sec}^{-1}$	
7	8.00	7.74	$SiO_2 = 5 \text{ Å sec}^{-1}$	
9	3.85	3.66	Partial pressure of oxygen = 1×10^{-4} tor	
11	1.60	1.57		
13	0 · 70	0.67		
15	0.30	0.28		
17	0.15	0.12		
19	0.05	0.05		
21	<0.05	0.02		

room temperature in vacuum chamber and they attained the temperature of about 150° C during the deposition of multilayer. The above mirrors were deposited taking optimum deposition parameters as:

- (a) (i) Partial pressure of oxygen 1×10^{-4} torr.
- (b) (ii) The deposition rate 2.5 Å sec⁻¹ and 5 Å sec⁻¹ for TiO₂ and SiO₂ respectively.

The corresponding refractive indices are measured and found to be 2.30 and 1.50 at 6328 Å.

The above conditions were maintained constant during the deposition of the multilayers. The transmittance of the 21 layer mirror is nearly zero (< 0.05).

(iv) Stability and Structure of the Films

The following tests were carried out to establish the adhesion and stability of the films.

- (1) A strip of scotch tape was fixed to the surface of the mirror and pulled perpendicular to the substrate. This did not cause any damage to the mirror.
- (2) No damage was observed by rubbing the films with the usual pencil eraser.
- (3) No change was observed on the surface and in the reflectance values of the mirrors, when they were immersed in water for 24 hours and also in 5% sodium chloride solution for 24 hours.
- (4) The mirrors were not affected by acids like Concentrated. HCl, H₂SO₄ and HNO₃ and organic solvents.
 - (5) The mirrors were stable even at 400° C.
- (6) The surfaces of the single and multilayer films of TiO2 and SiO2 appear to be uniform, free from structural defects and scattering centres as observed under high magnification microscope (× 50).

These mirrors can be cleaned with acetone and soft linen cloth without causing any damage. Removal of the films can be done only by repolishing the substrate.

CONCLUSION

The optimum deposition parameters for the fabrication of multilayer films of TiO2 and SiO2 are summarised as follows:

- (i) Partial pressure of oxygen should be at 8×10^{-5} to 1×10^{-4} tor.
- (ii) Deposition rates should be 2.5 Å/sec.-1 and 5 Å/sec-1 for TiO and SiO respectively.

The characteristic absorption bands in IR and UV regions for SiO, Si₂O₃ and SiO₂ and TiO₂ and the above optimum deposition parameters are in good agreement with the reported values. A new absorption band is observed for TiO₂ film at 7.00μ .

The multilayer films produced by the above technique are durable, stable reproduceable.

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REFERENCES

[1]	Auwarter, M.	• •	U.S. Talent 2,920,002, 1962.
[2]	Ritter, E.	9 •	Optica Acta, 1962, 9, 197.
[3]	Anastasio, T. A.		J. Appl. Phys., 1966, 38, 2606.
[4]	Howson, H. P. et al.	(*)*·	Thin Solid Films, 1971, 9, 109.
[5]	Ritter, E.	• : • :	J. Vac. Sci. Technol., 1966, 3, 225.
[6]	Dundenhausen, B. et al.	•:•	Z. Angew Phys., 1969, 27, 191.
[7]	Heitman, W.		Appl. Opt., 1971, 10, 2414.
[8]	Heitman, W.		Appl. Opt., 1971, 10, 2685.
[9]	Narasimha Rao, K. and Ramakrishna Rao, M		Technical Report C.I.S.L., Indian Institute of Science, Bangalore, 1973.

[10] Narasimha Rao, K. and Ramakrishna Rao, M.

Quantum and Optoelectronic Symposium Proceedings, Bhabha Atomic Research Centre, Bombay, 1974.

[11] Heavens, O. S. .. Physics of Thin Films, G. Hass and R. E. Thun, eds.,
Academic Press, New York, 1964.

[12] Heitman, W. .. Thin Solid Films, 1970, 5, 61.